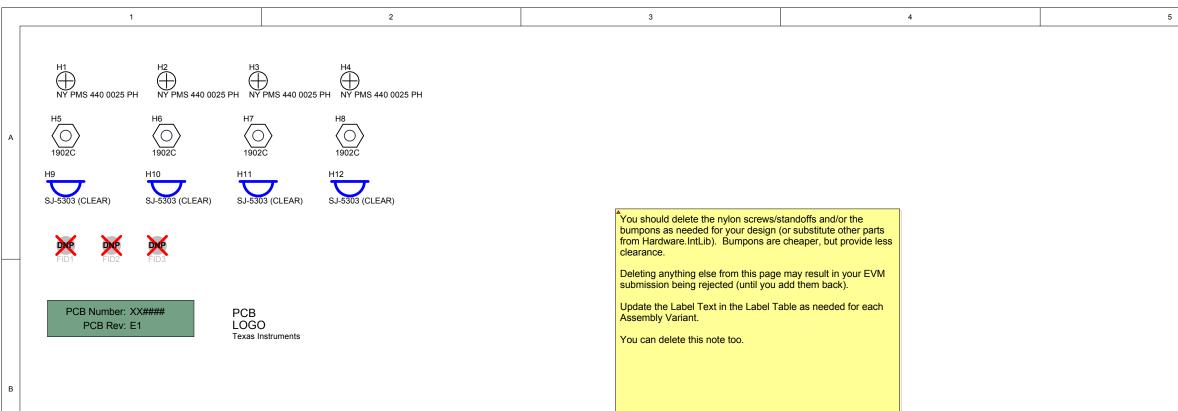


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LBL1		
PCB Label		
Size: 0.65" x 0.20 "		

ZZ1 Label Assembly Note This Assembly Note is for PCB labels only

Variant	Label Text
001	ChangeMe!
002	ChangeMe!

Label Table

1

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4 <sup>LL-7</sup>Assembly Note These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

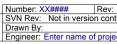
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 Number: XX####
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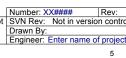
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	Revision History	
Revision	Notes	

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